

## MEMS Reliability Short Course

**Wednesday, May 28th 2008**

9:00 to 12:30 - **MEMS Technologies**

- What MEMS are for? What are the next killer applications?
- Physical principles used in Commercial sensors and actuators, status of technological trends.

14:00 to 17:30 - **Reliability Issues**

- State of the art of failure mechanisms, FMEA on main MEMS applications.
- State of the art of characterization techniques, Qualification plans.

This training course is provided by NOVA MEMS, a French (Toulouse) firm specialized in MEMS qualification. Please visit NOVA MEMS' website for any more information about its course program.

### Session 1 Industrial needs

**Thursday, May 29th 2008 - 9.30 to 12.30**

**DGA** : Xavier Grison "Defence requirements on MEMS"

**ESA** : Laurent Marchand

**CSA** : Wanping Zheng "MEMS Technologies in Canadian Space Programs"

Coffee break

**Airbus** : Jean-Pierre Daniel "MEMS reliability for Aeronautics"

**EADS Astrium ST** : Thierry Abensur "Space Transportation needs on Reliability & Safety"

**Thales Alenia Space** : Claude Drevon , Olivier Vendier, Jean-Louis Cazaux & Michel Sotom "T.A.S. Needs : Global Vision / RF MEMS / Optical MEMS switches"

**CNES** : Gian Andrea Quadri " Optical MOEMS reliability in space environment"

### Session 2 Technology Providers

**Thursday, May 29th 2008 - 14.00 to 17.00**

**Tronics** : Stephane Renard "Reliability of "high performance" accelerometers' vacuum packaging".

**Freescale** : Frederic Puel

**Silmach** : "MEMS design : reliability vs cost"

Coffee break

**Infineon** : Claudia Keller "Investigation of MEMS sensors by typical methods of semiconductor failure analysis"

**Auxitrol & LAAS** : Sebastiano Brida & JF Le Neal "Wafer level package for aerospace"

**Colibrys** : Jean-Michel Stauffer "Motion sensors for hostile environmental applications"

## Technical Visits

**Thursday, May 29th 2008**

17:00-19:00 - Technical Tour, Lab visits (NOVA MEMS, LAAS, CNES).

## Session 3 Reliability labs

**Friday, May 30th 2008 - 8.30 to 10.30**

Introduction speaker : **NOVA MEMS** : Xavier Lafontan

**CEA** : Didier Bloch "MEMS Failure Analysis : CEA-LETI activities introduction + Case Study "

**LIRMM** : Norbert Dumas "MEMS tests (embedded / in prod chain)"

**LAAS** : Fabio Coccetti "RF-MEMS Reliability Status and Perspectives"

**XLIM** : Arnaud Pothier + Pierre Blondy "Reliability Study of Dielectric Less Electrostatic Actuators: Application to MEMS Switches"

## Open Session

**Friday, May 30th 2008 - 10.30 to 11.30**

**IEF** : Fabien Parrain & Jean-Paul Gilles (Institute of Fundamental Electronic)

**LAAS** : David Peyrou "thin films characterisation & multi physical modelisation"

**Eumirel** : EUMIREL cluster's projects & activities

**SUSS MicroTEC**

**IMS** : Bruno Levrier "EURELNET"

## Session 4 Existing initiatives

**Friday, May 30th 2008 - 11.30AM to 12.30AM**

**LIRMM** : Laurent Latorre "ANR MIDISPPi project - packaging's environmental control (Temperature, humidity, pressure)"

**MEMUNITY**

**EADS CCR** : Bruno Foucher " EDA Research - POLYNOE Implementation of Physics Of Failure for MEMS"

## Project CANEUS Reliability Pilot Project

**Friday, May 30th 2008 - 13.45 to 17:00**

13.45 to 14.30 - **CANEUS Framework**

14.30 to 15.00 - **MNT-MEMS Reliability Pilot Project** : previous activities, CANEUS Vision

15.00 to 16.30 - **Partner's solicitation** : Networks' development & Project investment  
16:30 to 17:00 - **Summary**